

#### Description

The TWS817X1 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic DIP4 package with different lead forming options. With the robust coplanar double mold structure, TWS817X1 series provide the most stable isolation feature.

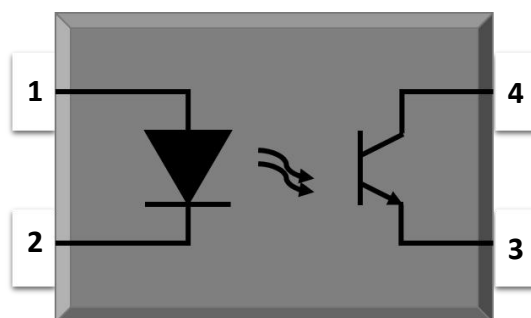
#### Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- RoHS & REACH Compliance
- MSL class 1
- Halogen free (Optional)
- Regulatory Approvals

#### Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

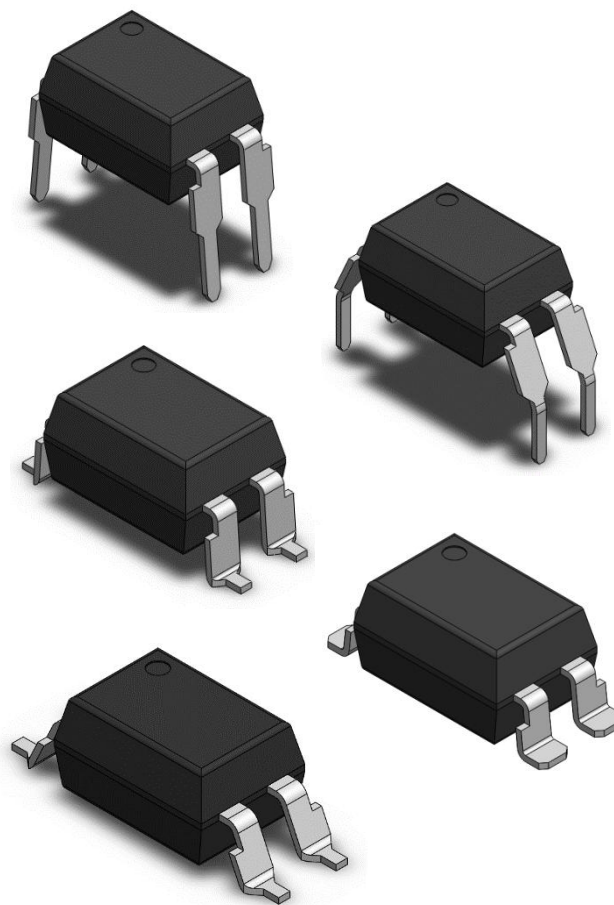
#### SCHEMATIC



#### PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

#### PACKAGE OUTLINE



<b>ABSOLUTE MAXIMUM RATINGS</b>				
PARAMETER	SYMBOL	VALUE	UNIT	NOTE
<b>INPUT</b>				
Forward Current	$I_F$	60	mA	
Peak Forward Current	$I_{FP}$	1	A	1
Reverse Voltage	$V_R$	6	V	
Input Power Dissipation	$P_I$	100	mW	
<b>OUTPUT</b>				
Collector - Emitter Voltage	$V_{CEO}$	35	V	
Emitter - Collector Voltage	$V_{ECO}$	6	V	
Collector Current	$I_C$	50	mA	
Output Power Dissipation	$P_O$	150	mW	
<b>COMMON</b>				
Total Power Dissipation	$P_{tot}$	200	mW	
Isolation Voltage	$V_{iso}$	5000	V <sub>rms</sub>	2
Operating Temperature	$T_{opr}$	-55~110	°C	
Storage Temperature	$T_{stg}$	-55~125	°C	
Soldering Temperature	$T_{sol}$	260	°C	

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%

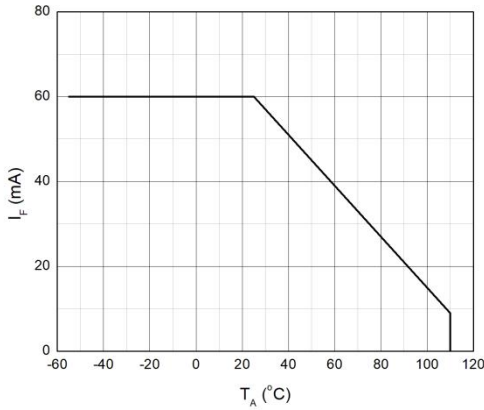
ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C								
PARAMETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE	
INPUT								
Forward Voltage	V <sub>F</sub>	-	1.24	1.4	V	IF=10mA		
Reverse Current	I <sub>R</sub>	-	-	10	μA	VR=6V		
Input Capacitance	C <sub>in</sub>	-	10	-	pF	V=0, f=1kHz		
OUTPUT								
Collector Dark Current	I <sub>CEO</sub>	-	-	100	nA	VCE=20V, IF=0		
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	35	-	-	V	IC=0.1mA, IF=0		
Emitter-Collector Breakdown Voltage	BV <sub>ECO</sub>	6	-	-	V	IE=0.1mA, IF=0		
TRANSFER CHARACTERISTICS								
Current Transfer Ratio	TWS817A1	CTR	80	-	160	%	IF=5mA, VCE=5V	
	TWS817B1		130	-	260			
	TWS817C1		200	-	400			
	TWS817D1		300	-	600			
	TWS817E1		100	-	200			
	TWS817F1		150	-	300			
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	-	0.06	0.2	V	IF=20mA, IC=1mA		
Isolation Resistance	R <sub>ISO</sub>	10 <sup>12</sup>	10 <sup>14</sup>	-	Ω	DC500V, 40 ~ 60% R.H.		
Floating Capacitance	C <sub>IO</sub>	-	0.4	1	pF	V=0, f=1MHz		
Response Time (Rise)	t <sub>r</sub>	-	3	18	μs	VCE=2V, IC=2mA	3	
Response Time (Fall)	t <sub>f</sub>	-	4	18	μs	RL=100Ω	3	
Cut-off Frequency	f <sub>c</sub>	-	80	-	kHz	VCE=2V, IC=2mA RL=100Ω, -3dB	4	

Note 3. Fig.12&13

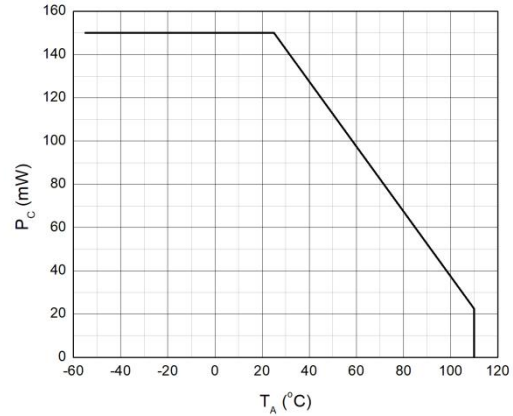
Note 4. Fig.14

#### CHARACTERISTIC CURVES

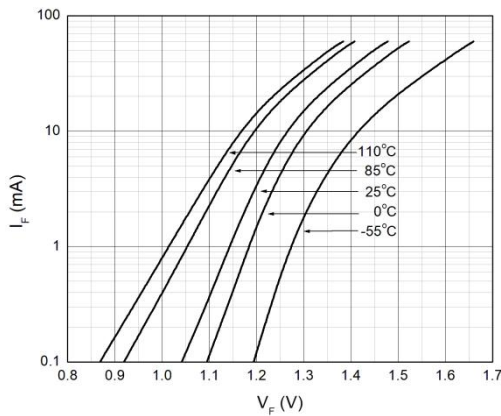
**Fig.1 Forward Current vs. Ambient Temperature**



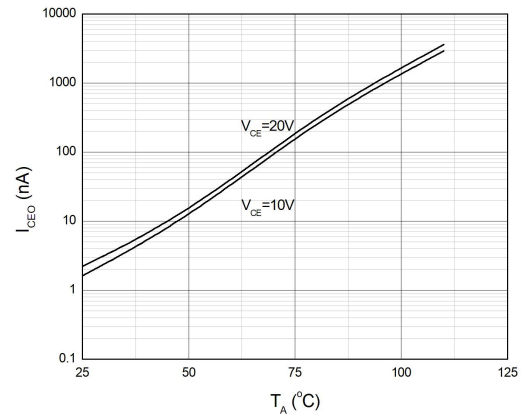
**Fig.2 Collector Power Dissipation vs. Ambient Temperature**



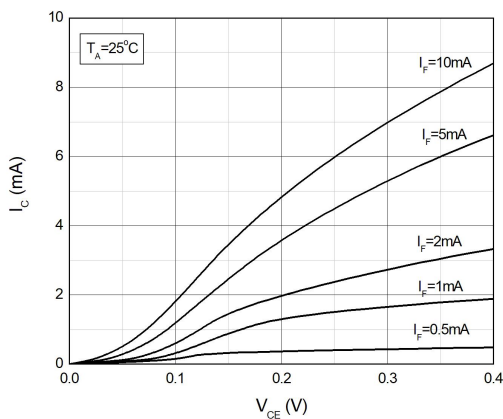
**Fig.3 Forward Current vs. Forward Voltage**



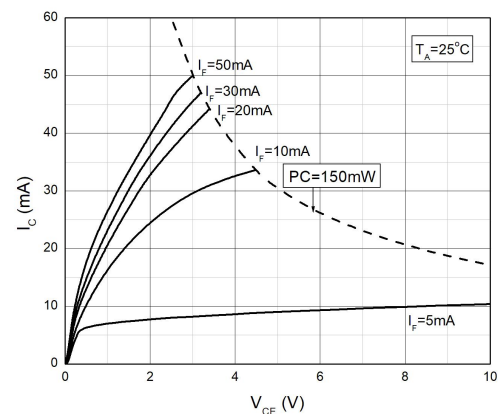
**Fig.4 Collector Dark Current vs. Ambient Temperature**



**Fig.5 Collector Current vs. Collector-emitter Voltage**

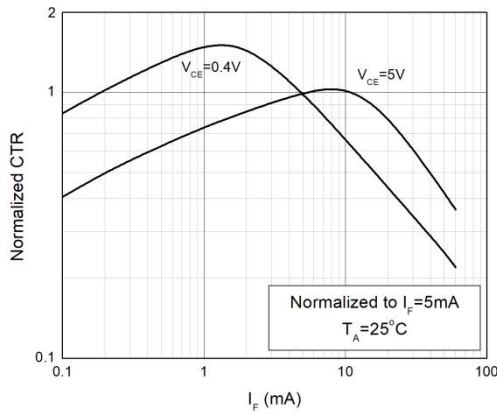


**Fig.6 Collector Current vs. Collector-emitter Voltage**

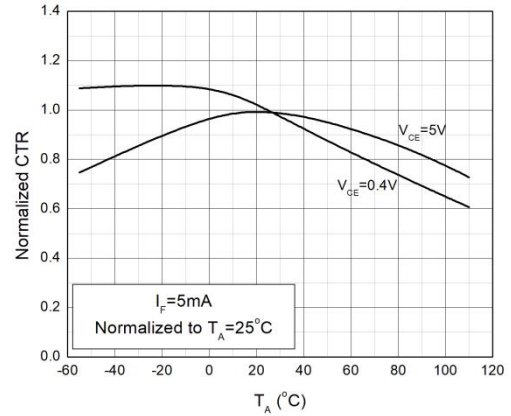


#### CHARACTERISTIC CURVES

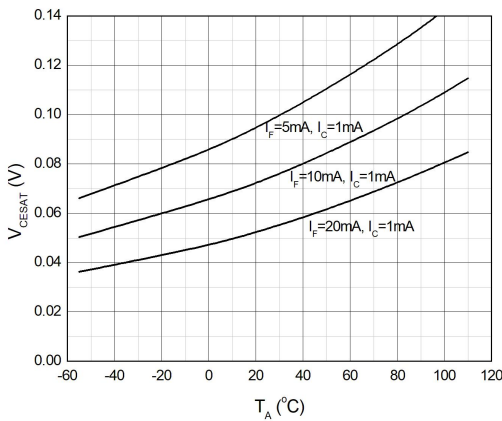
**Fig.7 Normalized Current Transfer Ratio vs. Forward Current**



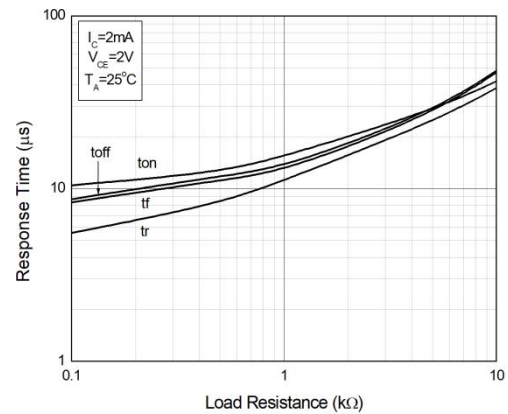
**Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature**



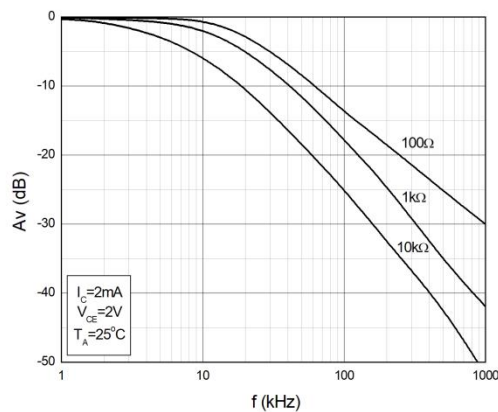
**Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature**



**Fig.10 Switching Time vs. Load Resistance**

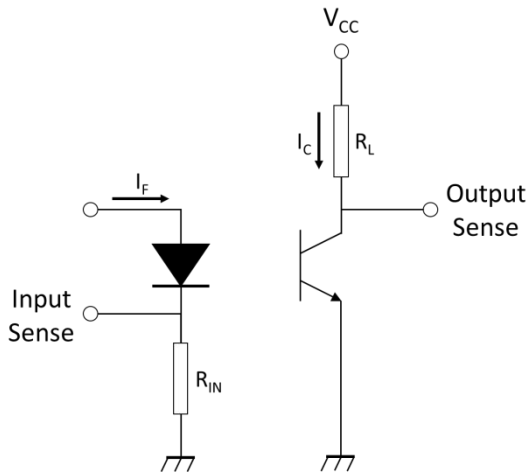


**Fig.11 Frequency Response**

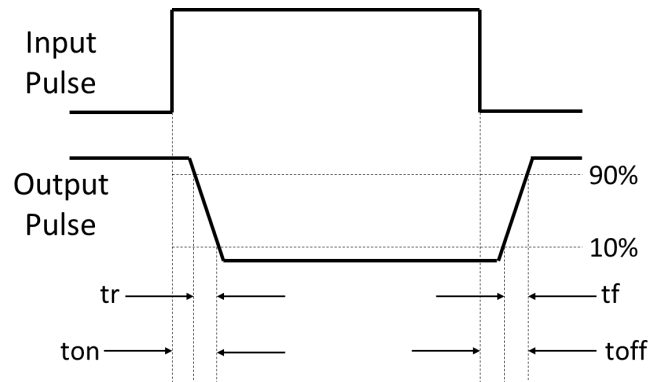


#### TEST CIRCUITS

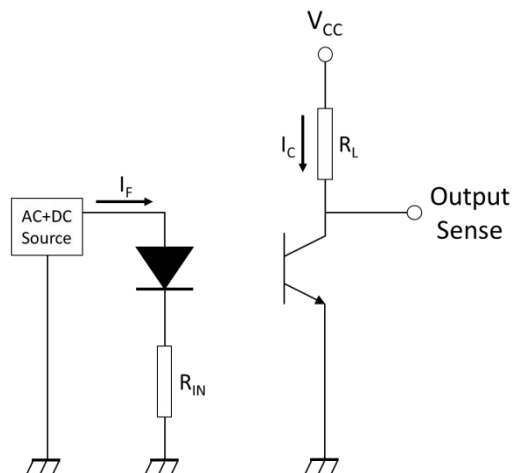
**Fig.12 Test Circuits of Response Time**



**Fig.13 Curves of Response Time**

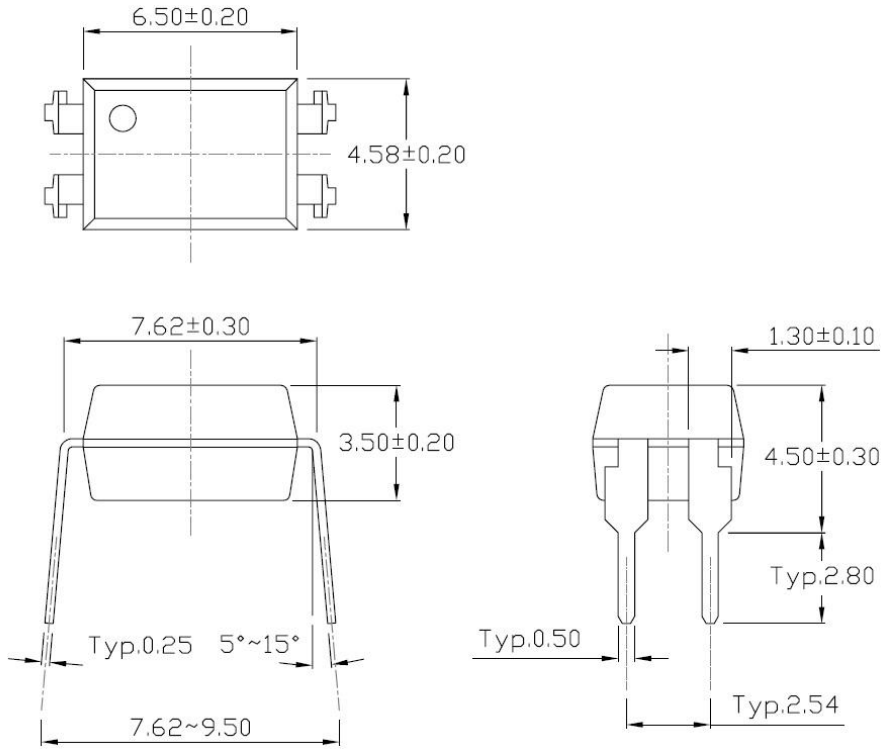


**Fig.14 Test Circuits of Frequency Response**

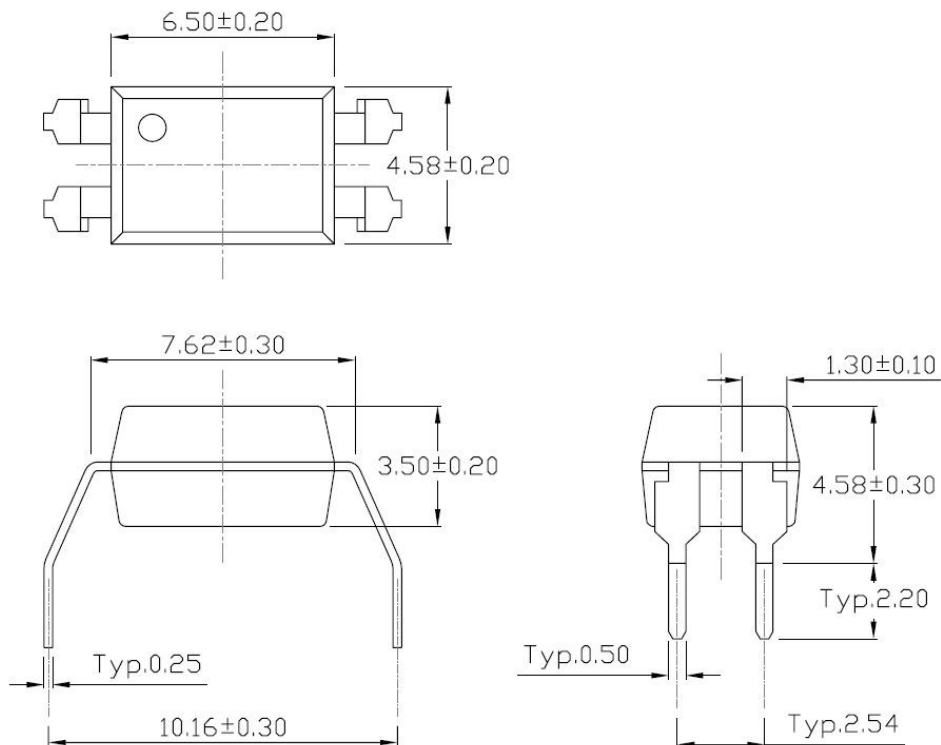


**PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)**

**Standard DIP – Through Hole (DIP Type)**

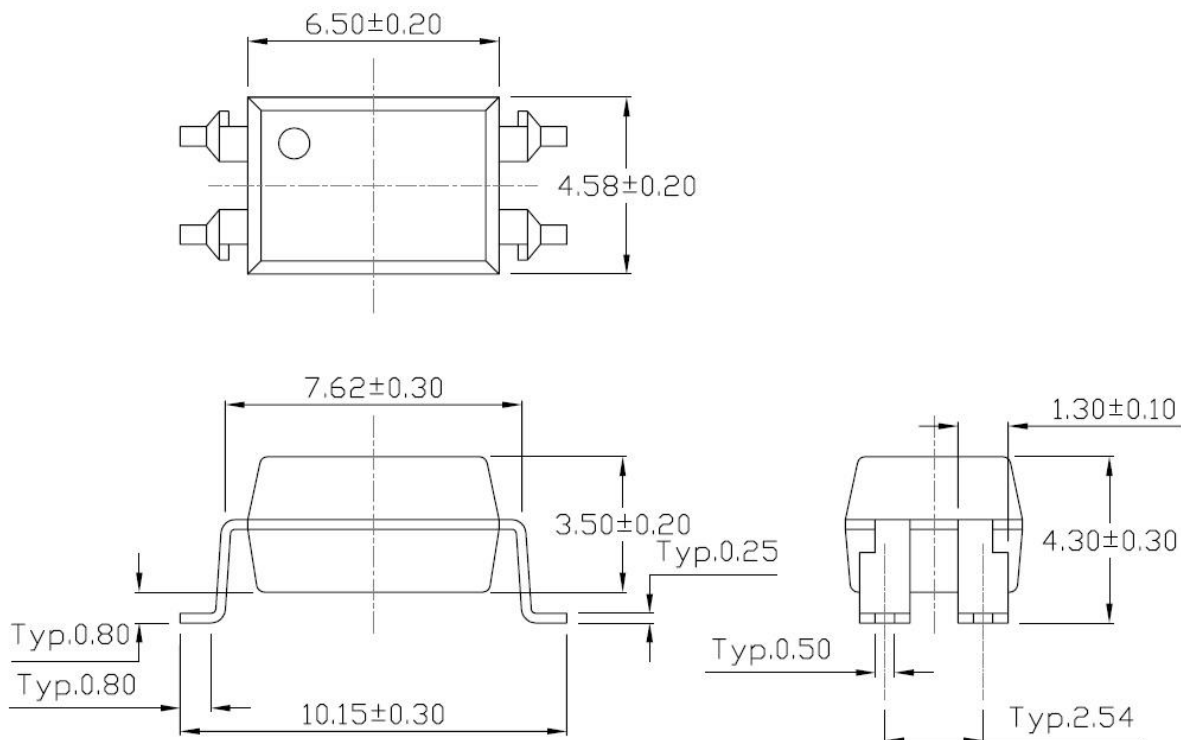


**Gullwing (400mil) Lead Forming – Through Hole (M Type)**

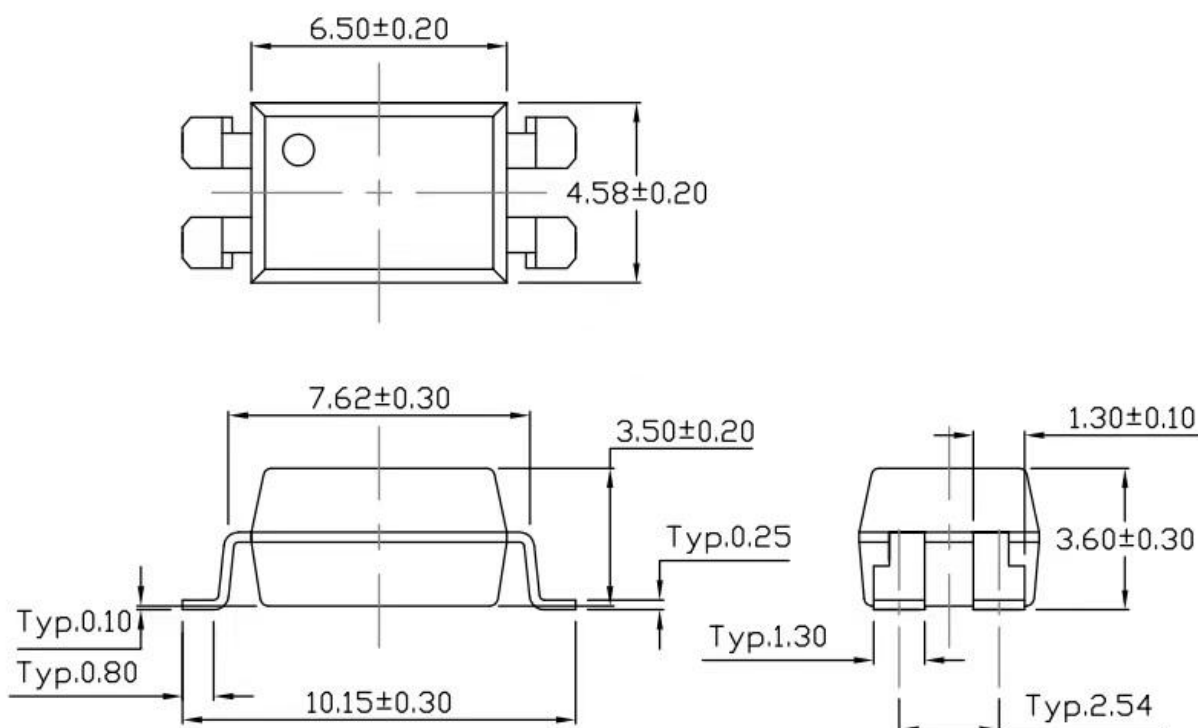


**PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)**

**Surface Mount Lead Forming (S Type)**



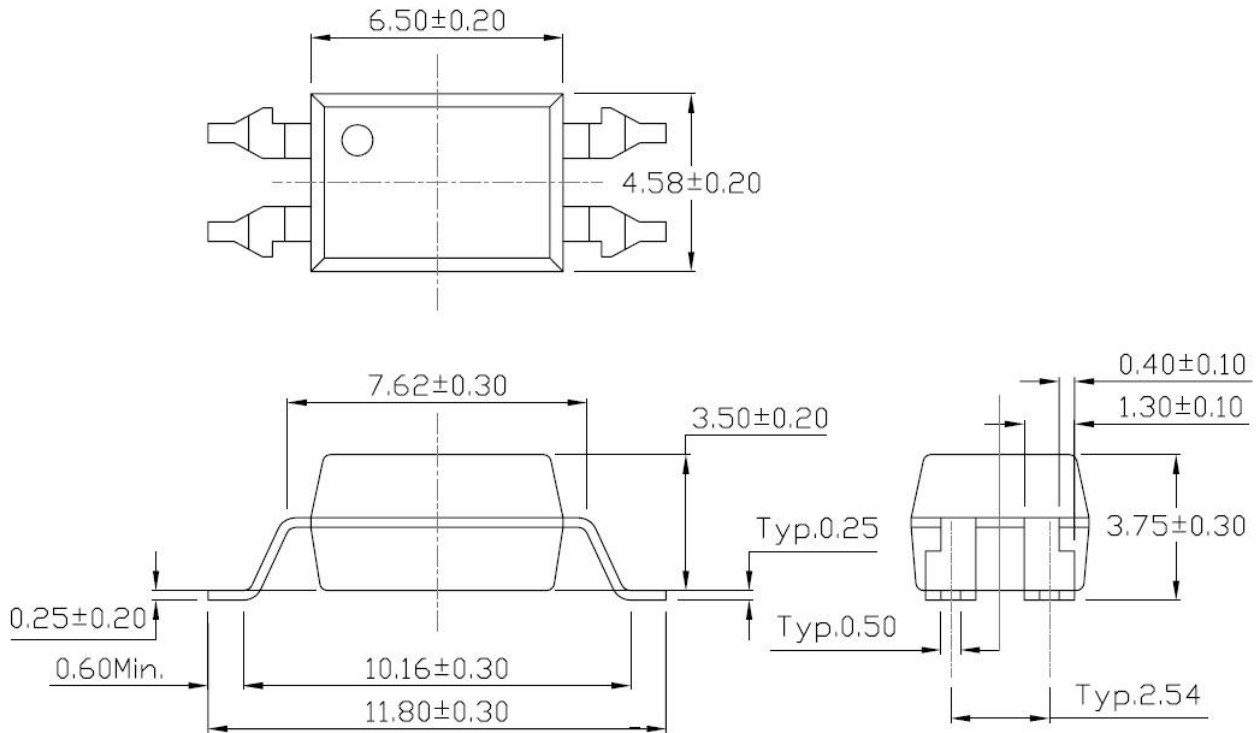
**Surface Mount (Low Profile) Lead Forming (SL Type)**





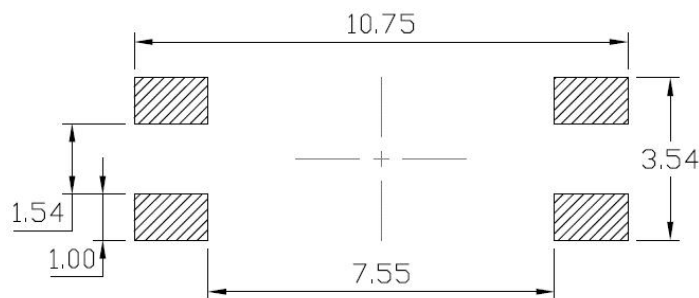
**PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)**

**Surface Mount (Gullwing) Lead Forming (SLM Type)**

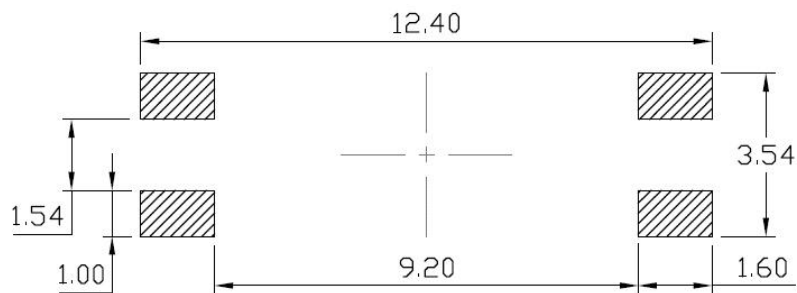


**RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)**

**Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming**

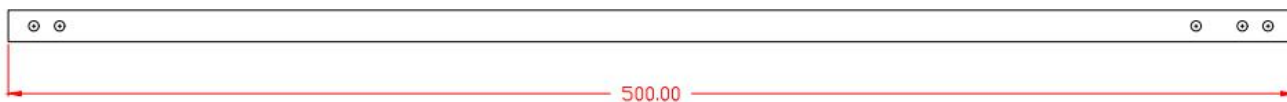
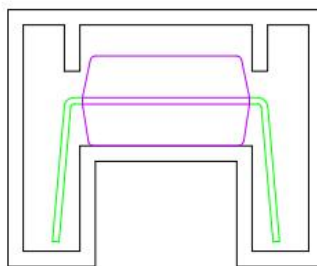
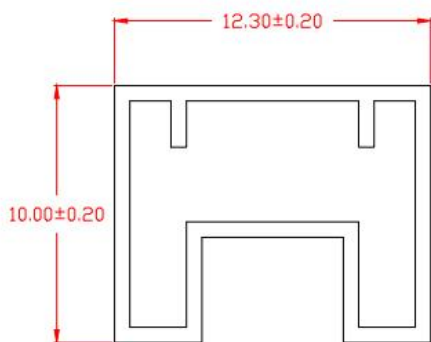


**Surface Mount (Gullwing) Lead Forming**



#### TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP / M



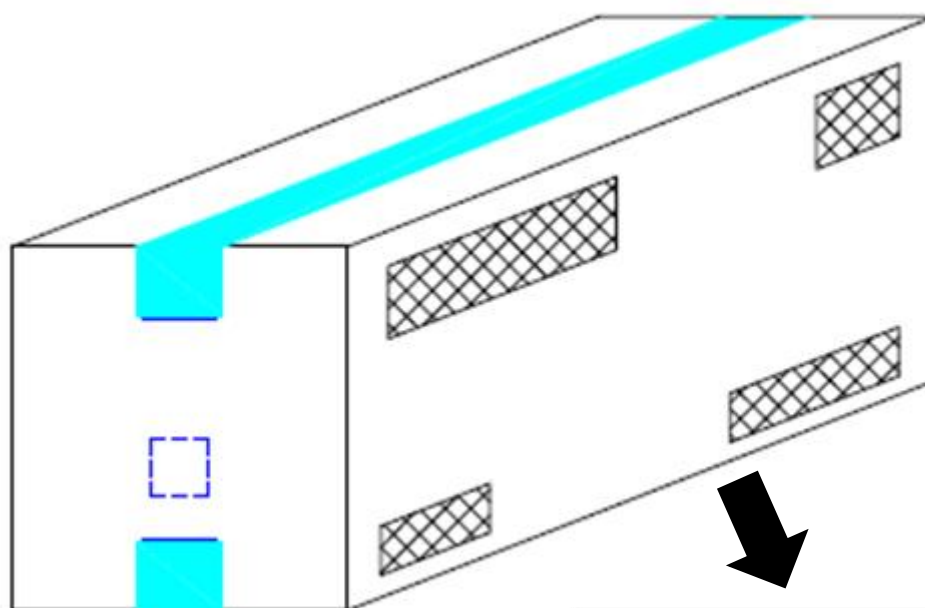
#### BOX SPECIFICATIONS (Tube Type)

#### Inner Box

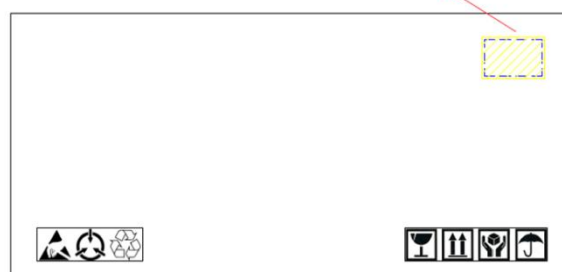


- L x W x H = 52.5cm x 10.7cm x 4.7cm

#### Outer Box

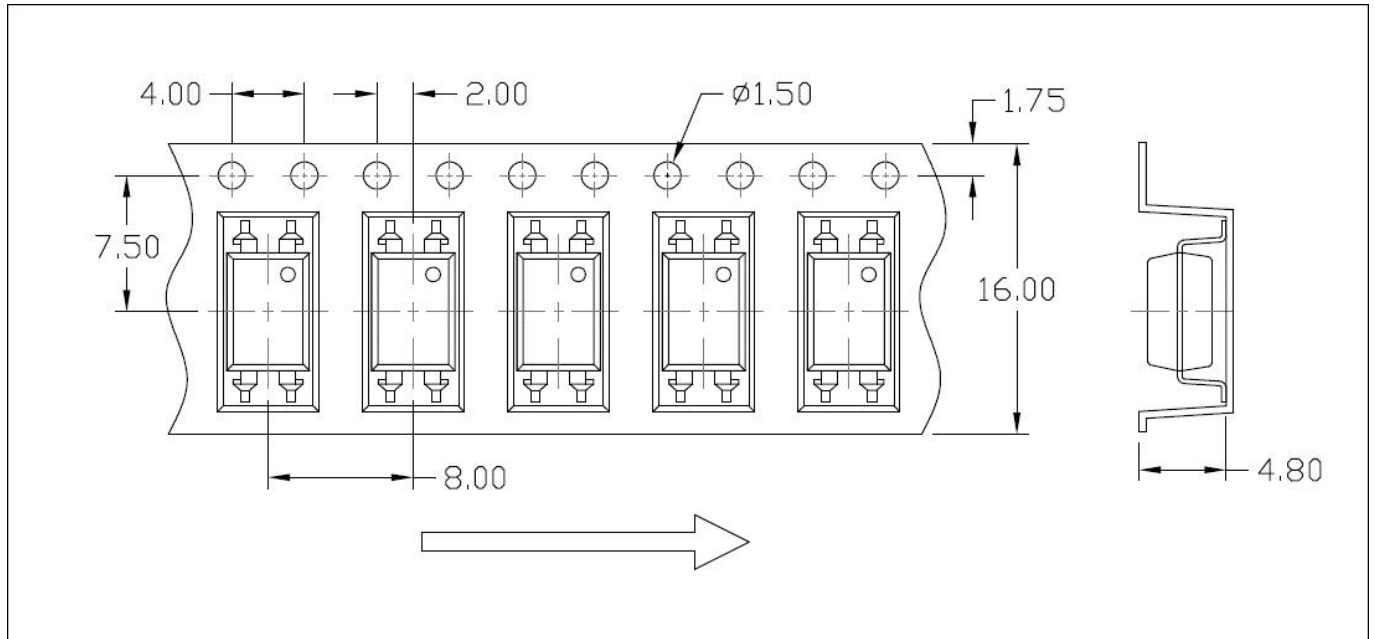


- L x W x H = 53.5cm x 23.5cm x 25.5cm

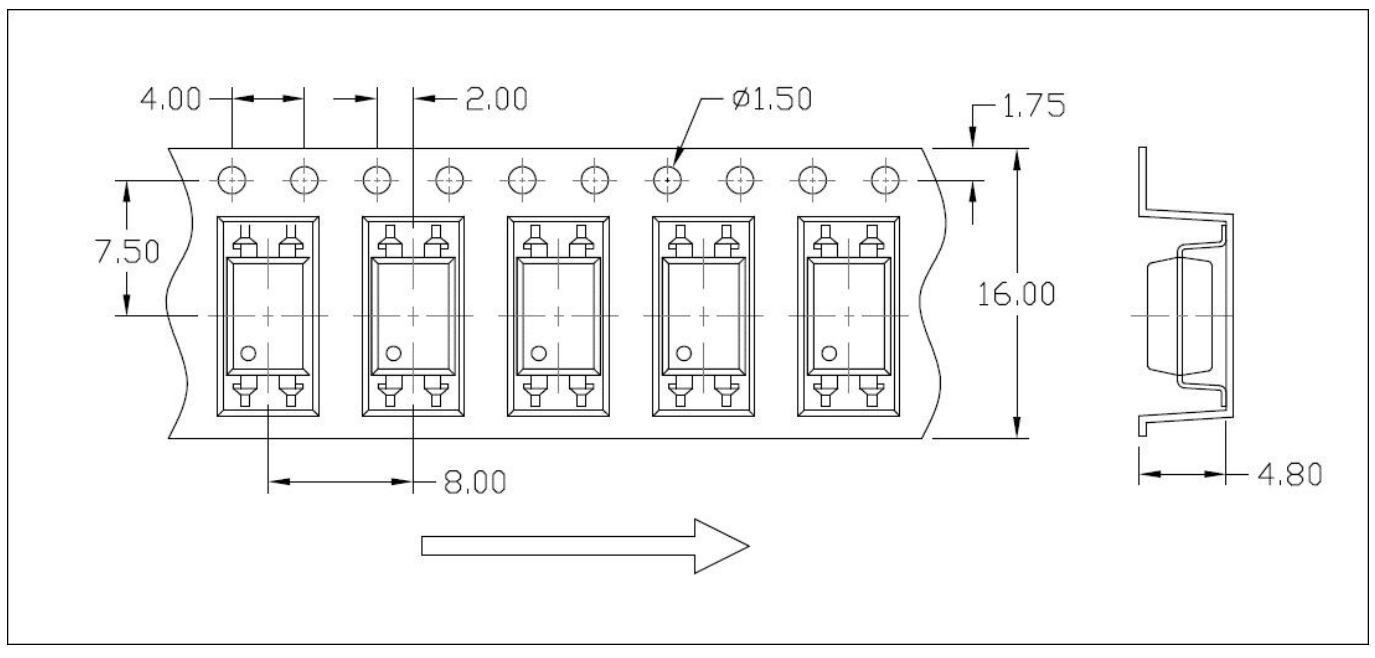


**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Option S(T1) & SL(T1)**

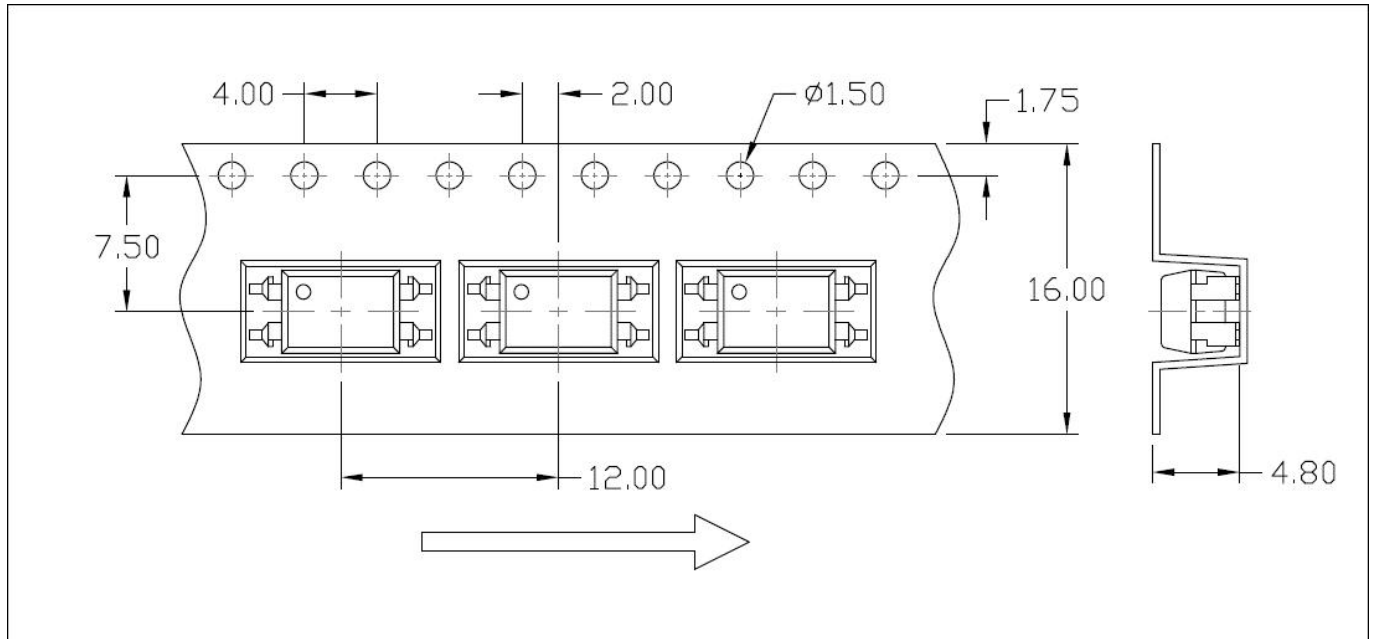


**Option S(T2) & SL(T2)**

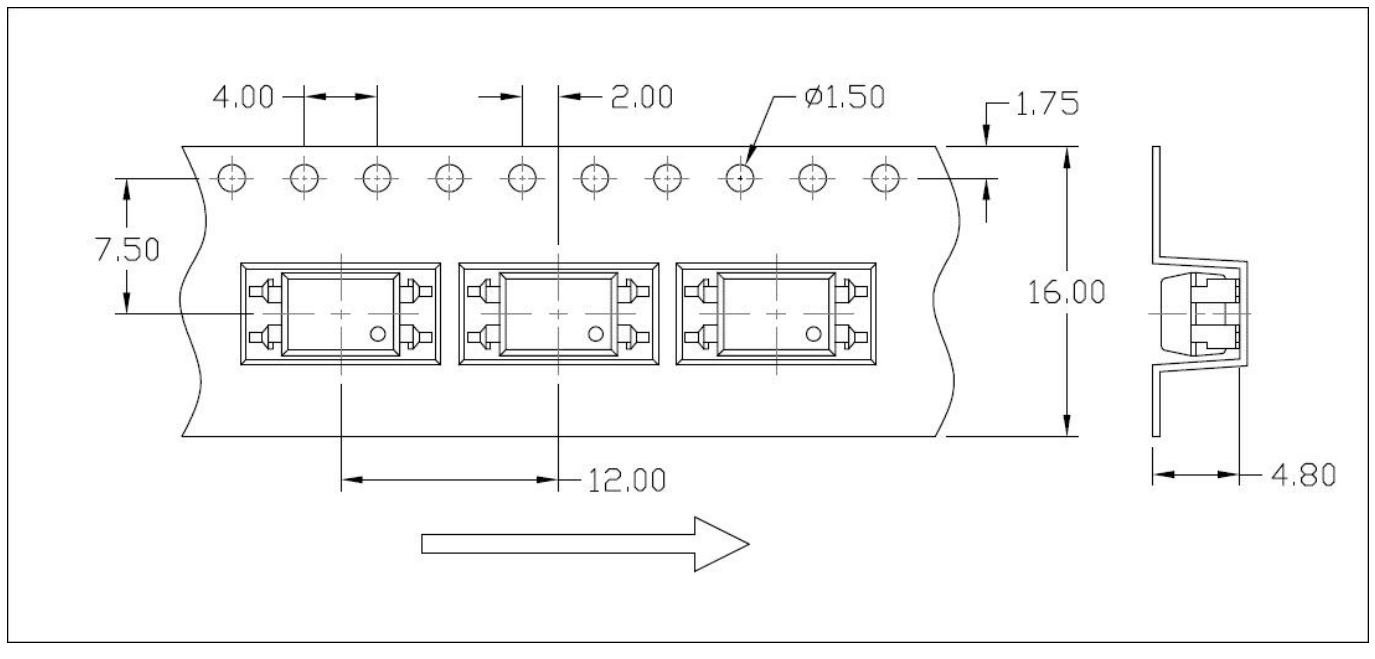


**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Option S(T3) & SL(T3)**

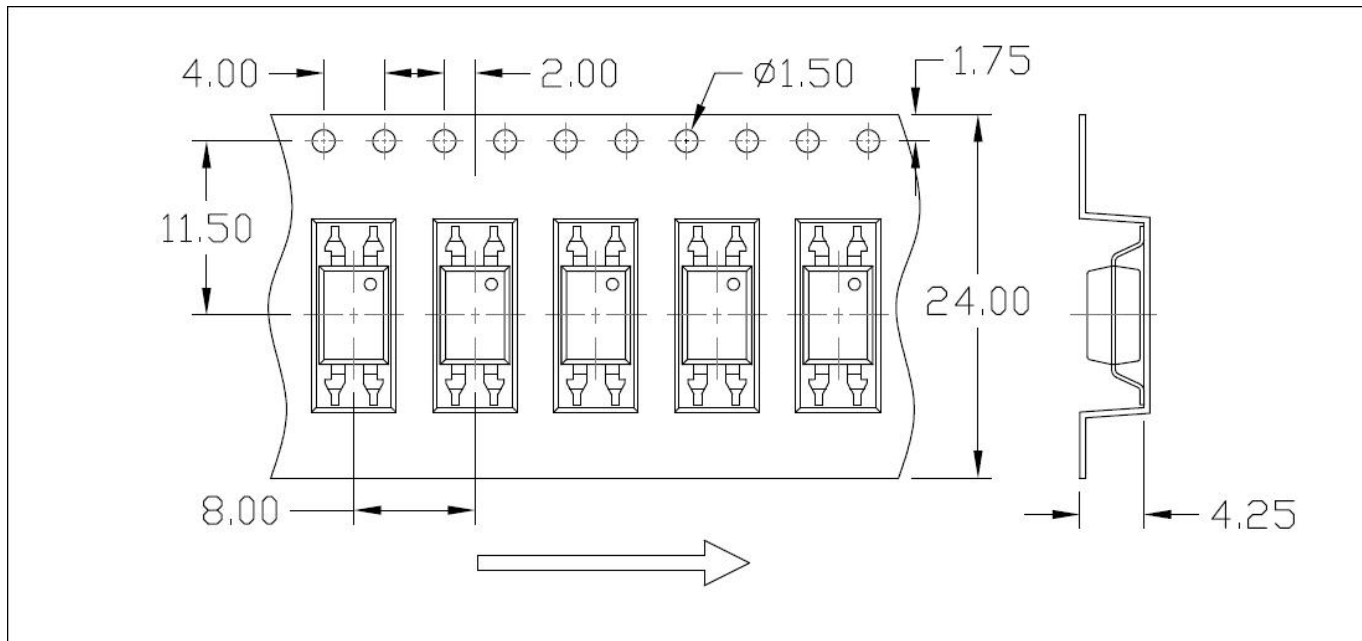


**Option S(T4) & SL(T4)**

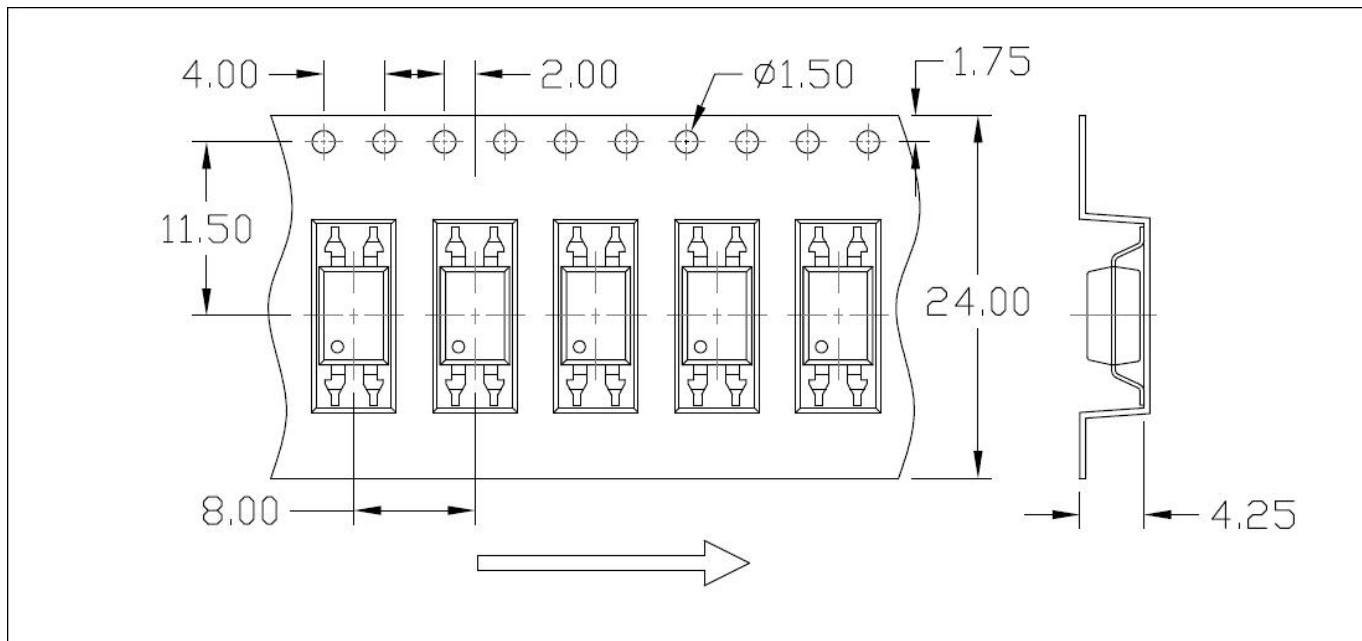


**CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)**

**Option SLM(T1)**

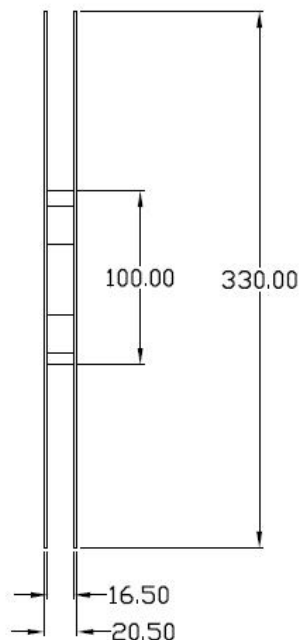
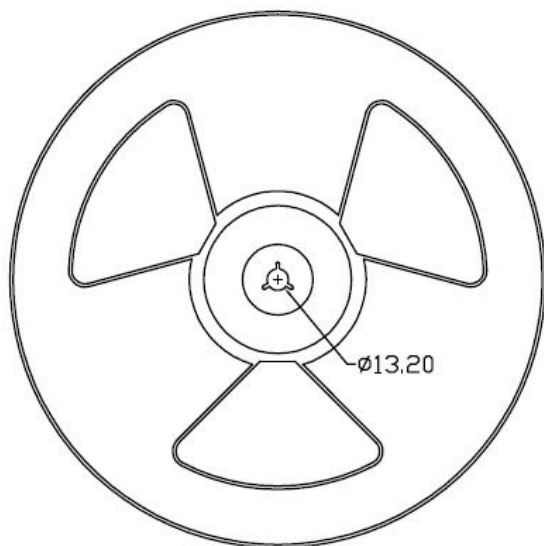


**Option SLM(T2)**

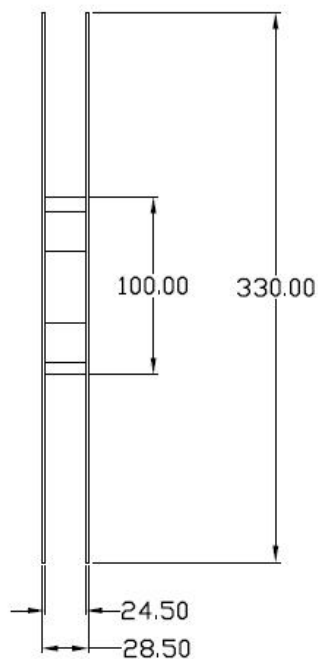
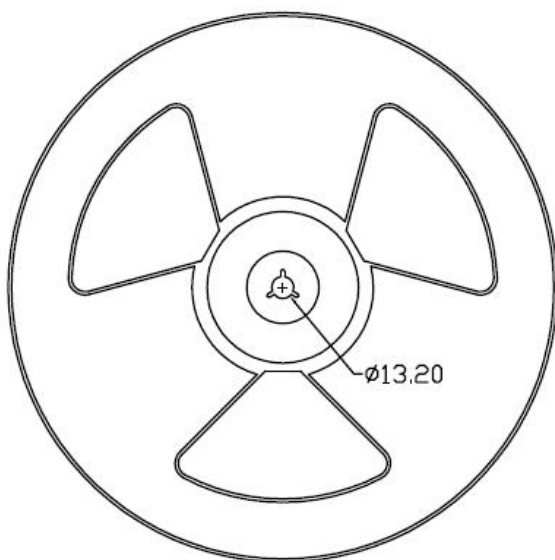


#### REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

##### Option S & Option SL



##### Option SLM



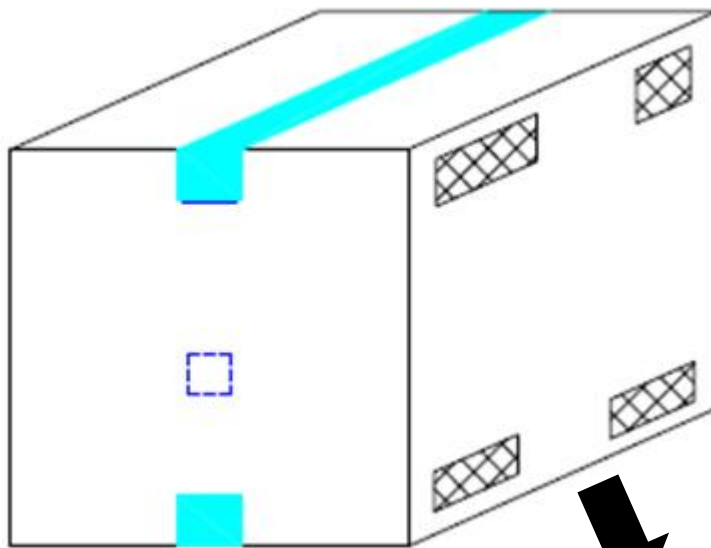
#### BOX SPECIFICATIONS (Reel Type)

##### Inner Box

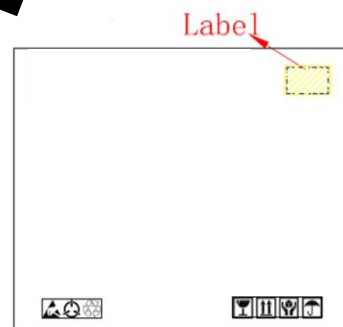


- L x W x H = 36cm x 36cm x 6.9cm

##### Outer Box



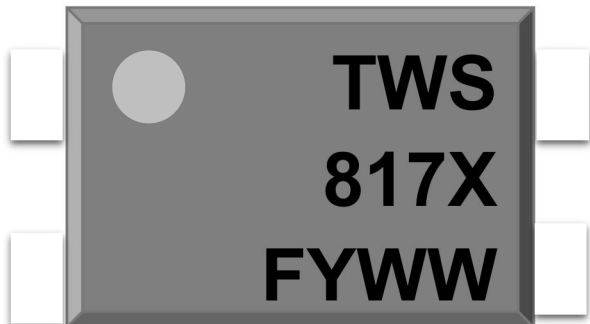
- L x W x H = 45cm x 38cm x 38cm





**ORDERING AND MARKING INFORMATION**

**MARKING INFORMATION**

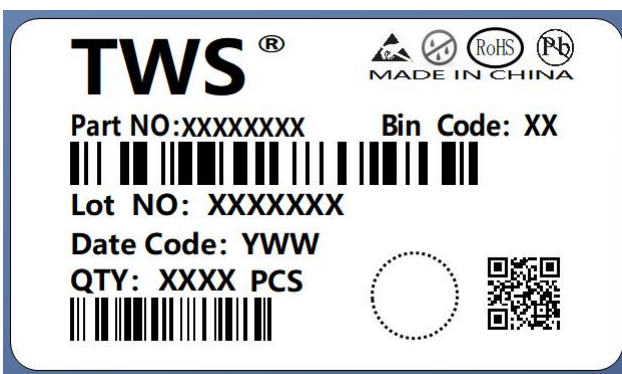


**TWS** : Company Abbr.  
**817** : Part Number  
**X** : CTR Rank  
**F** : Leadframe Option  
**Y** : Fiscal Year  
**WW** : Work Week

**ORDERING INFORMATION**

**LABEL INFORMATION**

**TWS817X1(Y)(Z)-FG**



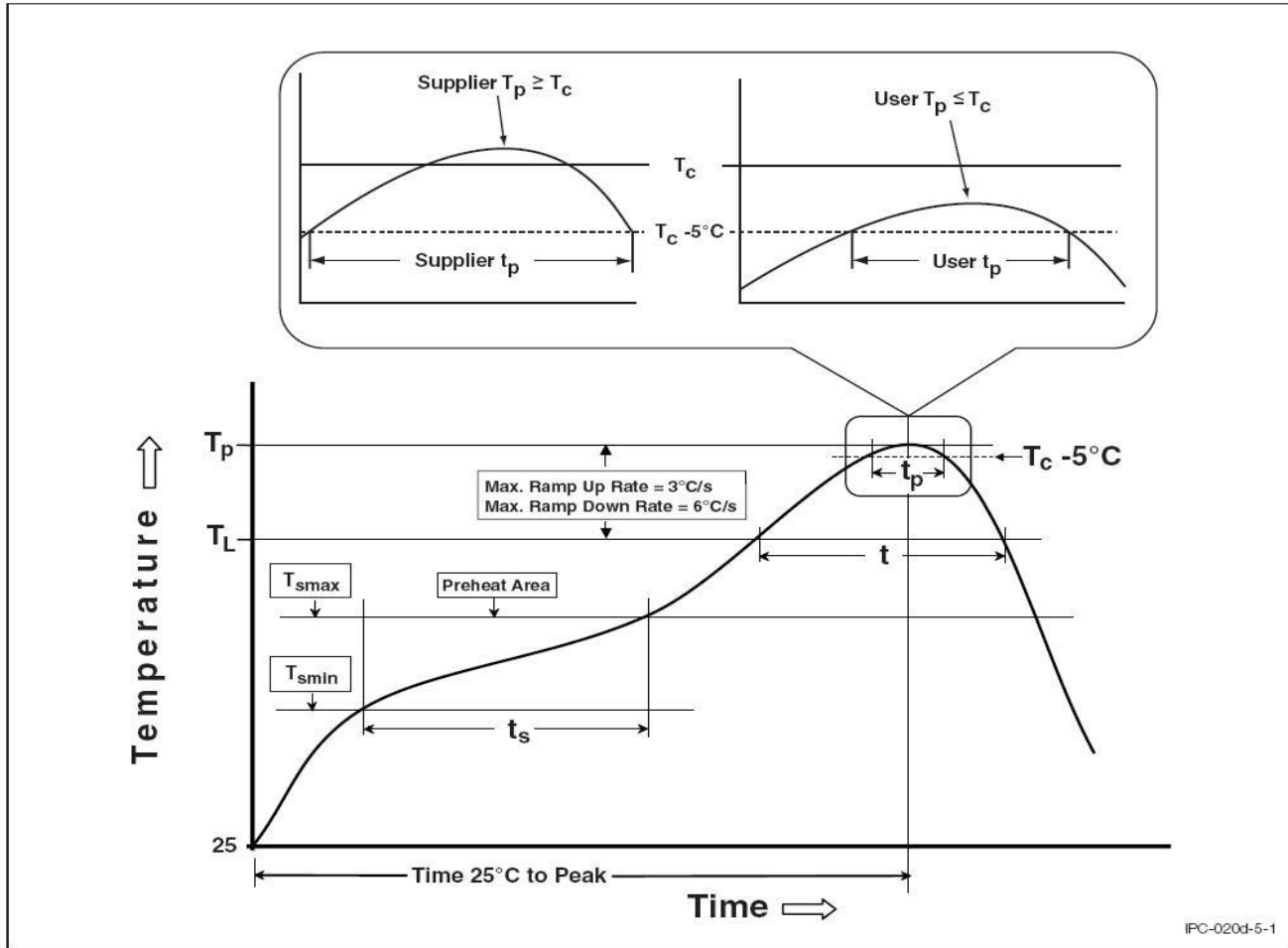
TWS – Company Abbr.  
 817 – Part Number  
 X1 – Rank (A1/B1/C1/D1)  
 Y – Lead Form Option (M/S/SL/SLM/None)  
 Z – Tape and Reel Option (T1/T2/T3/T4)  
 F – Leadframe Option (F:Iron, None:Copper)  
 G – Green

**Packing Quantity**

Option	Quantity	Quantity – Inner box	Quantity – Outer box
None	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 32k Units
M	100 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 32k Units
S(T1)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
S(T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
S(T3)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
S(T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T1)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
SL(T2)	1500 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 22.5k Units
SL(T3)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T4)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SLM(T1)	1500 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box = 15k Units
SLM(T2)	1500 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box = 15k Units

#### REFLOW INFORMATION

##### REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150°C
Temperature Max. (T <sub>smax</sub> )	150	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	183°C	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.